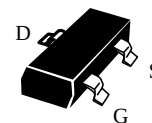


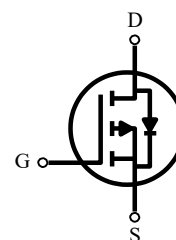
P-Channel Enhancement Mode MOSFET

SOT-23-3L



FEATURES

- Advanced Trench Technology
- Excellent RDS(ON) and Low Gate Charge
- Lead Free



ABSOLUTE MAXIMUM RATINGS ($T_A = 25\text{ }^{\circ}\text{C}$ unless otherwise noted)

Parameter		Symbol	Limit	Unit
Drain-Source Voltage		V_{DS}	-30	V
Gate-Source Voltage		V_{GS}	± 20	V
Drain Current-Continuous	$T_A=25^{\circ}\text{C}$	I_D	-8	A
	$T_A=100^{\circ}\text{C}$		-4.8	A
Drain Current-Continuous ¹		I_{DM}	-32	A
Maximum Power Dissipation	$T_A=25^{\circ}\text{C}$	P_D	2.5	W
Junction & Storage Temperature Range		T_J, T_{STG}	- 55 to 150	$^{\circ}\text{C}$

THERMAL CHARACTERISTICS

Thermal Resistance, Junction to Ambient ²	R_{thJA}	50	$^{\circ}\text{C}/\text{W}$
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- Notes:**
- 1.Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
 2. R_{thJA} is measured with the device mounted on a 1inch² pad of 2oz copper FR4 PCB

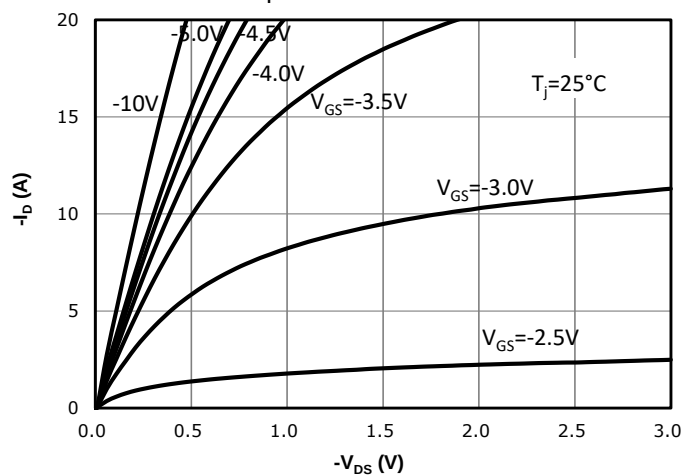
ELECTRICAL CHARACTERISTICS (TA = 25 °C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} = 0V , I _D = -250uA	-30			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = -30V , V _{GS} = 0V			-1.0	uA
Gate-Body Leakage	I _{GSS}	V _{GS} = ±20V , V _{DS} = 0V			±100	nA
ON CHARACTERISTICS						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = -250uA	-1.1	-1.6	-2.2	V
Drain-Source On-State Resistance ³	R _{DS(on)}	V _{GS} = -10V , I _D =-5A		16	20.8	mΩ
	R _{DS(on)}	V _{GS} = -4.5V , I _D = -3A		26	33.8	mΩ
DYNAMIC CHARACTERISTICS						
Input Capacitance	C _{ISS}	V _{DS} = -15V , V _{GS} = 0V f = 1.0MHz		900		pF
Output Capacitance	C _{OSS}			172		pF
Reverse Transfer Capacitance	C _{RSS}			146		pF
Total Gate Charge	Q _g	V _{GS} = 0 to -10V V _{DS} =-15V, I _D = -5A		22		nC
Gate-Source Charge	Q _{gs}			3		nC
Gate-Drain Charge	Q _{gd}			6		nC
SWITCHING CHARACTERISTICS						
Turn-On Delay Time	t _{D(ON)}	V _{GS} = -10V, V _{DD} = -15V I _D =-5A, R _{GEN} = 2.5Ω		10		ns
Rise Time	t _r			14		ns
Turn-Off Delay Time	t _{D(OFF)}			50		ns
Fall Time	t _f			20		ns
Drain-Source Diode Characteristics and Max Ratings						
Drain to Source Diode Forward Current	I _S				-8	A
Drain to Source Diode Forward Current	I _{SM}				-32	A
Drain to Source Diode Forward Voltage ³	V _{SD}	V _{GS} = 0V, I _S = -5A			-1.2	V
Body Diode Reverse Recovery Time	t _{rr}	I _F =-5A, di/dt = 100A/us		64		nS
Body Diode Reverse Recovery Charge	Q _{rr}			25		nC

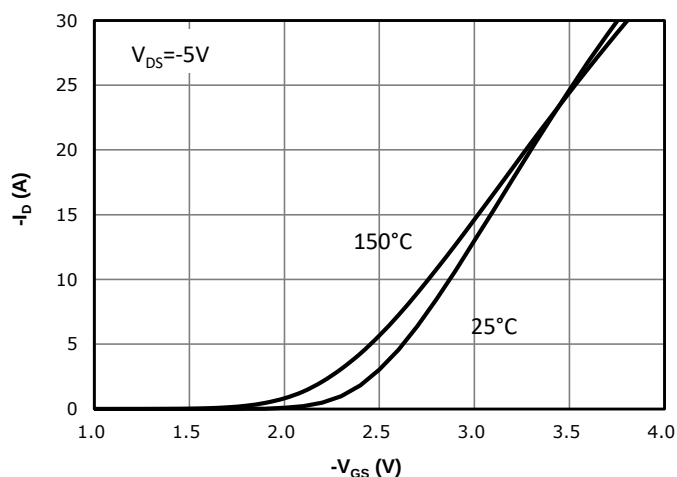
Note :3. Pulse Test: Pulse Width≤300μs, Duty Cycles≤0.5%.

Typical Characteristics

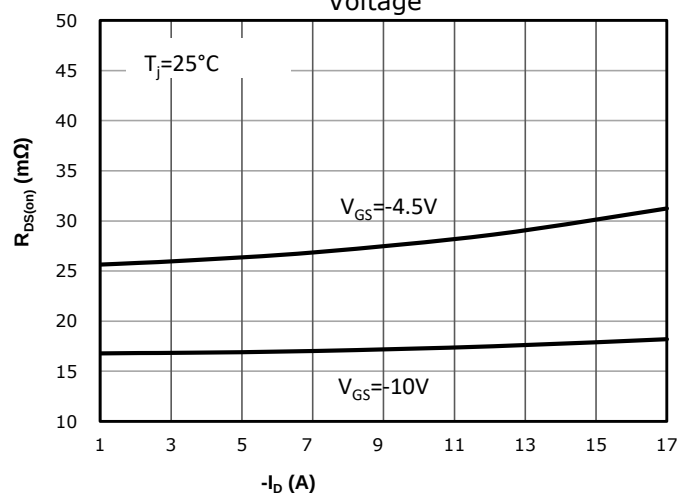
Output Characteristics



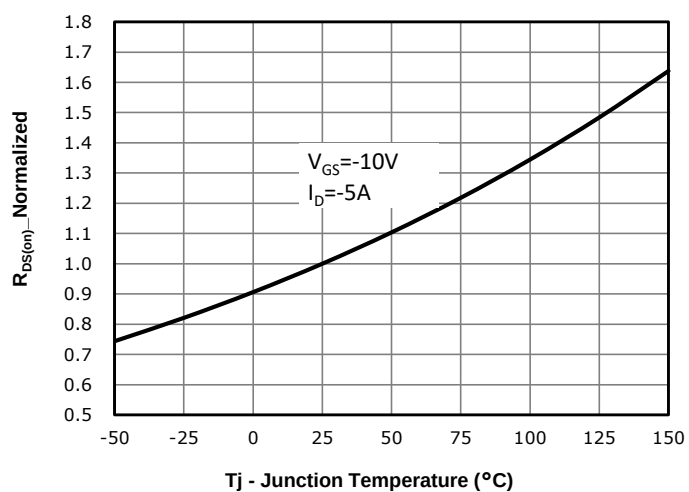
Transfer Characteristics



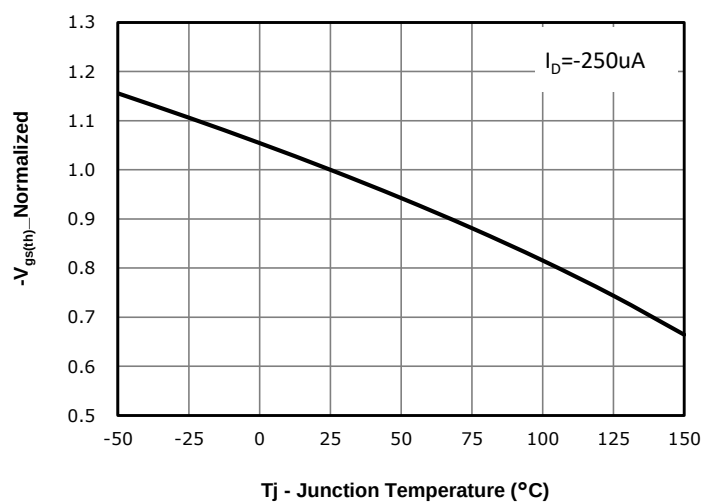
$R_{DS(on)}$ vs Drain Current and Gate Voltage



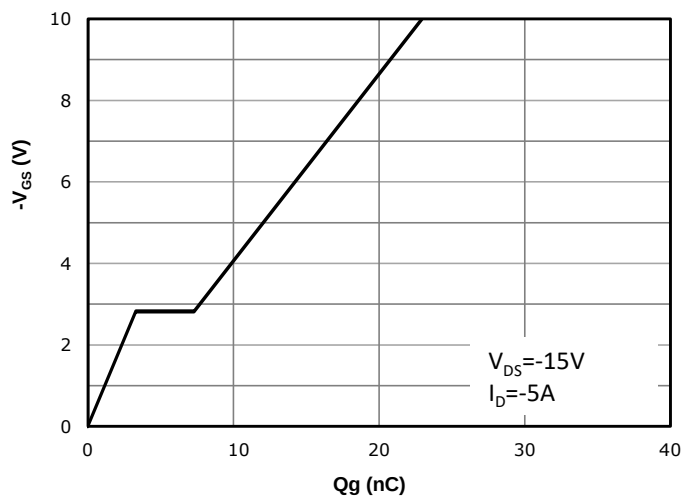
$R_{DS(on)}$ vs. Temperature



$V_{GS(th)}$ vs. Temperature

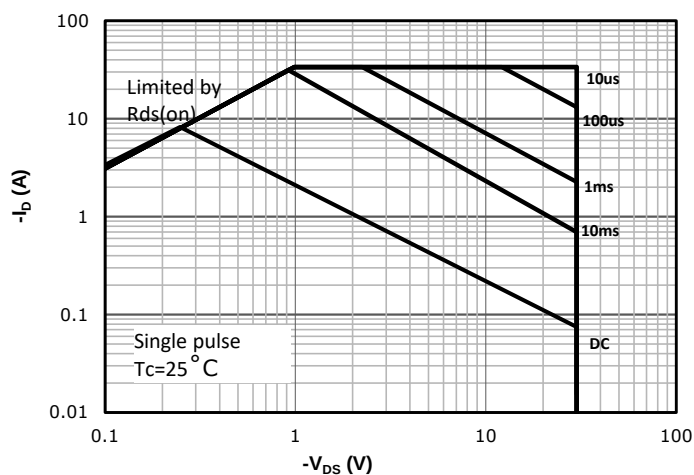


Gate Charge Characteristics

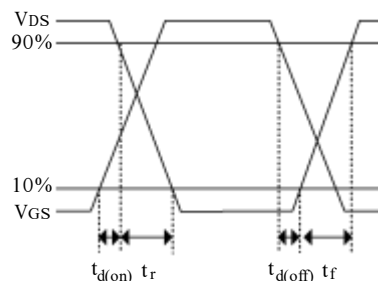
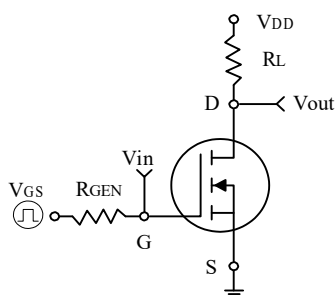
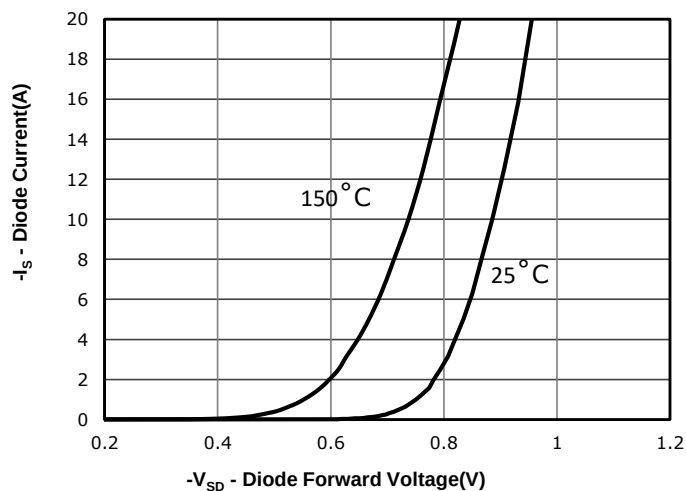


Typical Characteristics

Safe Operating Area



Body-diode Forward Characteristics



Switching Test Circuit and Switching Waveforms

Max. Transient Thermal Impedance

